

WHAT IS CLAIMED IS:

1. A method for providing an integrated circuit package with an alignment mechanism, comprising:
 - a) applying a pattern of contact pads to the integrated circuit package;
 - b) applying a number of annular ring shaped alignment pads to said integrated circuit package, at known locations with respect to said pattern of contact pads; and
 - c) attaching a number of alignment balls to said number of annular ring shaped alignment pads.
2. The method of claim 1, further comprising:
 - a) applying a wetting media to said number of annular ring shaped alignment pads; and
 - b) heating said wetting media; and
 - c) attaching said number of alignment balls to said number of annular ring shaped alignment pads while said wetting media is heated.
3. The method of claim 1, further comprising applying said pattern of contact pads and number of annular ring shaped alignment pads to the integrated circuit package at the same time.
4. The method of claim 1, further comprising choosing said alignment balls to have diameters that are greater than the diameters of their corresponding alignment pads.
5. The method of claim 1, wherein the number of alignment balls attached is three.
6. A method for providing an integrated circuit package with an

alignment mechanism, comprising:

- a) heating a wetting media that has been applied to a number of annular ring shaped alignment pads provided on said integrated circuit package at known locations with respect to a pattern of contacts pads provided on said integrated circuit package; and
 - b) attaching a number of alignment balls to said number of annular ring shaped alignment pads while said wetting media is heated.
7. The method of claim 6, further comprising choosing said alignment balls to have diameters that are greater than the diameters of their corresponding alignment pads.
8. The method of claim 6, wherein the number of alignment balls attached is three.
9. A method for providing an integrated circuit package with an alignment mechanism, comprising:
- a) heating a wetting media that has been applied to a number of annular ring shaped alignment pads provided on said integrated circuit package at known locations with respect to a pattern of contacts pads provided on said integrated circuit package; and
 - b) attaching a number of alignment bullets to said number of annular ring shaped alignment pads while said wetting media is heated.
10. The method of claim 9, wherein at least one of said alignment bullets has an end which is shaped to protrude into one of said number of annular ring shaped alignment pads, and wherein the method further comprises placing said end of said alignment bullet in contact with the

wetting media which is applied to one of said alignment pads.

11. The method of claim 10, wherein one of said alignment bullet ends that protrudes into an annular ring shaped alignment pad comprises a raised disc.
12. The method of claim 9, wherein the number of alignment bullets attached is three.